

An Initiative of the COMSNETS Association

6th International Conference

AI-ML Systems 2026

October 6-9, 2026 | Politecnico di Milano Campus in Lecco (Lecco), Italy.

www.aimlsystems.org

<https://cmt3.research.microsoft.com/AIMLSystems2026/>



CALL FOR WORKSHOP PROPOSALS

Submit your workshop proposal targeting the connections between Artificial Intelligence, Machine Learning, and Systems Engineering.

SCOPE

AIMLSystems 2026 welcomes proposals covering both focused topics aligned with conference tracks (academia, industry, EU projects, applications) and cutting-edge, forward-looking themes driven by leading researchers or industry experts.

- Enhance the technical program
- Foster discussion on emerging and focused topics
- Promote interaction between academia, industry, and research labs
- Support EU projects and industry-driven initiatives

Topics include:

scalable learning · AI infrastructures · domain-specific AI · responsible AI, on top of AIMLSystems topics (check the website and the CFP).

FORMAT

Workshops may include:

- Research papers
- Invited talks/presentations
- Panels & discussions

Organizers can propose invited speakers and are encouraged to engage a relevant community of contributors.

SUBMISSION REQUIREMENTS

Each proposal must include:

- Title, type, duration
- Organizers (affiliations, bios, experience)
- Description (motivation, relevance, impact)
- Format and tentative speakers
- Target audience & expected attendance
- Promotion plan

Please refer to the **submission template** available on the website

IMPORTANT NOTES

No financial support for organizers or speakers. Logistic support provided by the conference

All papers must follow conference policies. Papers may be:

- Included in workshop proceedings, or
- Submitted to main conference tracks

SUBMIT YOUR PROPOSAL

Fill in the template and send it via email to:

luca.magri@polimi.it, andrea.ceni@unipi.it, subbareddyoota@gmail.com

IMPORTANT DATES

- **Workshop Proposal Deadline:** April 22, 2026
- **Notification of Workshop Acceptance:** April 30, 2026, decisions on a rolling basis
- **Workshop Paper Submission Deadline:**
 - June 8, 2026 (abstract)
 - June 15, 2026 (full papers)
- **Conference Dates:** October 6–9, 2026

ORGANISING COMMITTEE

- **General Co-Chairs**
 - Giacomo Boracchi, Politecnico di Milano, IT
 - Rekha Singhal, TCS Paceport, USA
 - Debdoot Mukherjee, Meesho, India
- **Technical Program Committee Co-Chairs**
 - Filippo Maria Bianchi, UiT, Norway
 - Fazel Keshtkar, St John's University, USA
 - Kalika Bali, Microsoft, India
- **Industry Track Co-Chairs**
 - Marco Tarabini, Politecnico di Milano
- **Workshop Co-Chairs**
 - Luca Magri, Politecnico di Milano, IT
 - Subba Reddy Oota, TU Berlin, DE
 - Andrea Ceni, Università Pisa, IT
- **Finance and Registration Co-Chairs**
 - Francesco Trovò, Politecnico di Milano, IT
 - Chandrika Sridhar, IISc Bangalore, India
 - Raj Sharma, Walmart Global Tech, India
- **Web Co-Chairs**
 - Ojaswa Varshney, IIIT Surat, India,
 - Joan Paul Breux, Louisiana State Univ., USA,
 - Shivani Singh, IT Bangalore, India
- **Publicity Co-Chairs**
 - Massimo Pavan, DTU, Denmark
 - Pradeep Singh IIIT Surat, India
 - Magesh Rajasekaran, Louisiana State Univ., USA
 - Carlos Becker Westphall, Univ. Santa Catarina, BR
- **Social Media Co-Chairs**
 - Alessandro Falcetta, Politecnico di Milano, IT
 - Arghya Kusum Das, Univ of Alaska Fairbanks, USA
 - Shantanu Pal, Deakin Univ, Australia
- **IT Co-Chairs**
 - Kaushik Chowhan, IIT Gandhinagar, India
- **Sponsorship Co-Chairs**
 - Rajeev Shorey, IIIT Surat, India,
 - Giridhar Mandyam, AMD, USA.
- **Local co-chairs**
 - Michele Craighero, Polimi, IT),
 - Carlotta Massotti, Polimi, IT.
- **Demos & Exhibits Co-Chairs**
 - Flavia Marrone, Polimi, IT,
 - Subba Reddy Oota, TU Berlin, DE
- **Steering Committee Co-Chairs**
 - Uday Desai, IIT Hyderabad, India,
 - G Venkatesh, IIT Madras, India,
 - Anurag Kumar, IISc Bangalore, India,
 - Giridhar Mandyam, AMD, USA,
 - Huzur Saran, IIT Delhi, India,
 - Rajeev Shorey, IIIT Surat, India,
 - Supratik Mukhopadhyay, Louisiana Univ., USA.